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APPLICATION NO.	FI	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/720,761 03/26/2001		03/26/2001	Franz Laermer	10191/1629	5642	
26646	7590	02/22/2006		EXAMINER		
KENYON	& KENY	ON LLP	CHEN, KIN CHAN			
ONE BROA	ADWAY					
NEW YOR	K, NY 10	0004	ART UNIT	PAPER NUMBER		
	•			1765	· <u> </u>	

DATE MAILED: 02/22/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

		A		Analis (1)	<i>X</i> _				
		Application No	•	Applicant(s)	$\omega$				
	Office Assistant Conservation	09/720,761		LAERMER ET AL.					
	Office Action Summary	Examiner		Art Unit					
· -		Kin-Chan Chen		1765					
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply									
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.  - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).									
Status	•								
1)⊠	Responsive to communication(s) filed on 17 Ja	anuary 2006.							
2a)⊠	This action is FINAL. 2b) This action is non-final.								
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the ments is								
closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.									
Disposition of Claims									
4)⊠ Claim(s) <u>19,21-24,27-36,39 and 40</u> is/are pending in the application.									
4a) Of the above claim(s) is/are withdrawn from consideration.									
5)⊠ Claim(s) <u>34-36 and 40</u> is/are allowed.									
6)	Claim(s) 19,21-24,27-33 and 39 is/are rejected	<b>).</b>							
7) 🗌	Claim(s) is/are objected to.								
8)[	Claim(s) are subject to restriction and/or	r election require	ement.		•				
Applicat	ion Papers								
9)[	The specification is objected to by the Examine	r.							
10)[	The drawing(s) filed on is/are: a) acce	epted or b) 🗌 ob	jected to by the E	Examiner.					
	Applicant may not request that any objection to the	drawing(s) be held	l in abeyance. See	37 CFR 1.85(a).					
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).									
11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.									
Priority	under 35 U.S.C. § 119								
-	Acknowledgment is made of a claim for foreign All b) Some * c) None of:	priority under 35	5 U.S.C. § 119(a)	-(d) or (f).					
	1. Certified copies of the priority documents	s have been rec	eived.						
2. Certified copies of the priority documents have been received in Application No									
3. Copies of the certified copies of the priority documents have been received in this National Stage									
application from the International Bureau (PCT Rule 17.2(a)).									
* See the attached detailed Office action for a list of the certified copies not received.									
Attachmer	nt(s)								
1) Notic	ce of References Cited (PTO-892)	4) 🗀	Interview Summary						
	ce of Draftsperson's Patent Drawing Review (PTO-948)	5, [	Paper No(s)/Mail Da	te atent Application (PTO-15	2)				
	rmation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) er No(s)/Mail Date	5) <u> </u>	Other:	atent Apphication (FTO-15)	<del>-</del> ,				
J.S. Patent and	Trademark Office			·					

#### **DETAILED ACTION**

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1. The examiner notes that claims 19, 21,22,24,27,29,31-33,35,and 36 in the current list of claims have numerous editorial (typographic) errors. Applicant is required to review and correct them. For examples, in clam 21, line 2, " $O_z$ " should be -- $O_2$ -. In claim 24, line 11, " $O_4F_3$ " should be --  $O_4F_8$ --.

#### Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 19, 21,22, 24, and 27 are rejected under under 35 U.S.C. 103(a) as obvious over Flamm et al (Journal of the Electrochemical Society, Dec. 1982, USA Bd 129, Nr.12, Page 2755-2760) in view of Kawasaki et al (US 4,795,529) as evidenced by Pu et al. (US 5,843,847).

Flamm teaches a method of anisotropic plasma etching a laterally defined structure in as silicon substrate using a process gas. Flamm teaches adding a fluorine-delivering etching gas to the process gas. The fluorine-delivering etching gas may include NF<sub>3</sub>, CIF<sub>3</sub> or BrF<sub>3</sub> (page 2756, col. 1, full paragraph 3). Flamm also teaches that plasma in a wide range of gas mixtures including CF<sub>4</sub>, CF<sub>4</sub>/O<sub>2</sub> and C<sub>2</sub>F<sub>6</sub>/O<sub>2</sub> can be

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used to supply fluorine atoms for selective isotropic silicon etching. The said gas mixtures can deposit polymer (so-called precipitating at least one passivating material in the instant claims), see page 2755, col. 1 and 2. Because it is known that gas comprising C<sub>2</sub>F<sub>6</sub> can supply fluorine atoms for selective isotropic silicon etching and deposit polymer and because it is disclosed by Flamm, hence, it would have been obvious to one with ordinary skill in the art to incorporate gas mixtures including CF<sub>4</sub>/O<sub>2</sub> and C<sub>2</sub>F<sub>6</sub>/ O<sub>2</sub> in the method of etching silicon using the fluorine-delivering etching gas including NF<sub>3</sub>, CIF<sub>3</sub> or BrF<sub>3</sub> (instant claims 19, 24, 25) and use them in any combinations thereof since they have been taught to be useful for the same purpose (etching silicon substrate), see Pu et al. (US 5,843,847; col. 1, line 62 through col. 2, line 4) as evidence for the "known" statement of depositing polymer as a passivating layer. The claimed invention differs from Flamm by using C<sub>4</sub>F<sub>8</sub>. In the method of plasma etching apparatus and method, Kawasaki (col. 18, line 45) teaches that C<sub>4</sub>F<sub>8</sub> may be used as etchant. Hence, it would have been obvious to one with ordinary skill in the art to use C<sub>4</sub>F<sub>8</sub> as etchant in the process of Flamm because each of which is taught to be useful to etch same kind of material.

"It is prima facie obvious to use two compositions (two methods) each of which is taught by the prior art to be useful for the same purpose." In re Kerkhoven 205 USPQ 1069 (CCPA 1980). In re Susi 169 USPQ 423, 426 (CCPA 1971). See also Ex parte Quadranti 25 USPQ 2d 1071 (BPAI 1992).

4. Claims 19, 21, 22, 24, and 27 are rejected under under 35 U.S.C. 103(a) as obvious over Sony (EP 0 414 372 A2) in view of Kawasaki et al (US 4,795,529) as evidenced by Pu et al. (US 5,843,847).

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Sony teaches a method of anisotropic plasma etching a defined structure in as silicon substrate using a process gas. Sony teaches adding a fluorine-delivering etching gas to the process gas. The fluorine-delivering etching gas may include CIF<sub>3</sub>. Sony also teaches that plasma in a wide range of gas mixtures including SiF<sub>4</sub>, Cl<sub>2</sub>/O<sub>2</sub>, and Cl<sub>2</sub>/N<sub>2</sub> can be used to supply fluorine atoms for selective isotropic silicon etching. The said gas mixtures can deposit protective layer (so-called precipitating at least one passivating material in the instant claims), (col.1 (page 2), lines 41-48; Col. 4 (page 3), lines 7-17). Sony teaches using dry etching to from a desired configuration in the silicon substrate. Sony is not particular about the desired configuration. Hence, it would have been obvious to one with ordinary skilled in the art to etch a laterally defined structure because it is one of the most popular structure in the semiconductor device fabrication. The claimed invention differs from Sony by using C<sub>4</sub>F<sub>8</sub>. In the method of plasma etching apparatus and method, Kawasaki teaches that C<sub>4</sub>F<sub>8</sub> may be used as etchant. Hence, it would have been obvious to one with ordinary skill in the art to use C<sub>4</sub>F<sub>8</sub> as etchant in the process of Sony because each of which is taught to be useful to etch same kind of material. Also see Pu et al. (US 5,843,847; col. 1, line 62 through col. 2, line 4) in the record as evidence for the "known" statement of depositing polymer as a passivating layer.

<sup>&</sup>quot;It is prima facie obvious to use two compositions (two methods) each of which is taught by the prior art to be useful for the same purpose." In re Kerkhoven 205 USPQ 1069 (CCPA 1980). In re Susi 169 USPQ 423, 426 (CCPA 1971). See also Ex parte Quadranti 25 USPQ 2d 1071 (BPAI 1992).

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5. Claims 23, 28, 29-33, and 39 are rejected under 35 U.S.C. 103(a) as being unpatentable over Flamm or Sony in view of Kawasaki et al as evidenced by Pu et al as applied to claims 19 and 24 above, and further in view of Meyer (US 5,182,234).

Unlike the claimed invention, the combined prior art (Flamm or Sony, Kawasaki, Pu) does not disclose that helium may be used in the process of etching silicon substrate. In the method of etching silicon substrate, Meyer teaches that helium may be used in the process of etching silicon substrate (col. 2, lines 65-68). Hence, it would have been obvious to one with ordinary skill in the art to incorporate helium as taught by Meyer in the process of the combined prior art in order to ensure the stability and promotes uniformity of the etching.

The above-cited claims specify the properties and effect of the light, ionized gas (e.g., improve selectivity, reduce charging effects, increase separation). However, the same materials are used with the same process. It appears that the method of the prior art would contain the same properties and functions as instantly claimed.

The discovery of a new property of a previously known composition, even if unobvious from the prior art, cannot impart patentability to such a composition. See In re Spada, 911 F.2d 705, 708, 15 USPQ2d 1655, 1657 (Fed. Cir. 1990).

Once a reference teaching product (composition) appearing to be substantially identical is made the basis of a rejection, and the examiner presents evidence of reasoning to show inherency, the burden shifts to the applicant to show an unobvious difference. Whether the rejection is based on "inherency" under 35 U.S.C. §102, or on "prima facie obviousness" under 35 U.S.C. §103, jointly or alternatively. In re Fitzgerald, 619 F.2d 67, 70, 205 USPQ 594, 596 (CCPA 1980). See also In re Best, 562 F.2d 1252, 1255, 195 USPQ 430, 433-34(CCPA 1977).

## Allowable Subject Matter

6. Claims 34-36 and 40 are allowed.

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### Conclusion

7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Pu et al. (US 5,843,847; col. 1, line 62 through col. 2, line 4) teaches that fluorocarbon gas forms polymeric by products that deposits as a passivating layer.

8. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

9. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Kin-Chan Chen whose telephone number is (703) 305-0222. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on (703) 305-2667. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

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Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-2934.

February 21, 2006

Kin-Chan Chen Primary Examiner Art Unit 1765